

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1997hms-2#pbf

(Engineering Calculation)

MSOP with 4 PINS REMOVED

(printed on: 2020-07-11 19:18:30)

**TOTAL MASS (g) : 0.038119**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003937	1000000	103281.757812		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013845	975000	363204.46875		
		Iron (Fe)	7439-89-6	0.000341	24000	8945.6640625		
		Phosphorus (P)	7723-14-0	0.000004	300	104.93447876		
		Zinc (Zn)	7440-66-6	0.000010	700	262.336181641		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.014200</b>	<b>1000000</b>	<b>372517.40625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000710	1000000	18626.5234375		
		<b>External Plating Total:</b>				<b>0.000710</b>	<b>1000000</b>	<b>18626.5234375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000086	1000000	2256.09130859		
<b>Internal Plating Total:</b>				<b>0.000086</b>	<b>1000000</b>	<b>2256.09130859</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000012	50000	314.803436279		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000074	300000	1941.2878418		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000161	650000	4223.61279297		
<b>Die Attach Total:</b>				<b>0.000247</b>	<b>1000000</b>	<b>6479.70361328</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001932	103000	50683.3515625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.016790	895000	440462.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000038	2000	996.877441406		
		<b>Encapsulation Total:</b>				<b>0.018760</b>	<b>1000000</b>	<b>492142.6875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000179	1000000	4695.81787109		
					<b>TOTAL MASS (g) :</b>	<b>0.038119</b>		